

# 16-BIT 2:1 MUX/DEMUX SWITCH

#### IDT74FST163233

#### **FFATURFS**:

- · Bus switches provide zero delay paths
- · Low switch on-resistance
- · TTL-compatible input and output levels
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- · Hot insertion capability
- · Very low power dissipation
- · Available in SSOP and TSSOP packages

## **DESCRIPTION:**

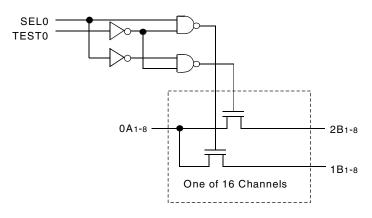
The FST163233 belongs to IDT's family of Bus switches. Bus switch devices perform the function of connecting or isolating two ports without providing any inherent current sink or source capability. Thus they generate little or no noise of their own while providing a low resistance path for an external driver. These devices connect input and output ports through an n-channel FET. When the gate-to-source junction of this FET is adequately forward-biased the device conducts and the resistance between input and output ports is small. Without adequate bias on the gate-to-source junction of the FET, the FET is turned off, therefore with no Vcc applied, the device has hot insertion capability.

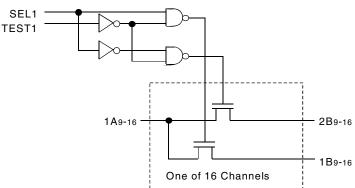
The low on-resistance and simplicity of the connection between input and output ports reduces the delay in this path to close to zero.

The FST163233 provides three 16-bit TTL-compatible ports that support 2:1 multiplexing. The SEL<sub>0,1</sub> and TEST<sub>0,1</sub> pins provide switch enable and mux select control as shown below.

The A port can be connected to port 1B or port 2B or both ports 1B and 2B.

## FUNCTIONAL BLOCK DIAGRAM



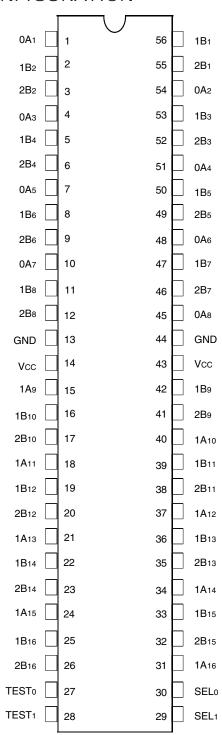


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INDUSTRIAL TEMPERATURE RANGE

**OCTOBER 2008** 

## **PIN CONFIGURATION**



SSOP/ TSSOP TOP VIEW

# ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +7	V
Tstg	Storage Temperature	-65 to +150	°C
Іоит	Maximum Continuous Channel Current	128	mA

#### NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. Vcc, Control, and Switch terminals.

## CAPACITANCE<sup>(1)</sup>

Symbol	Parameter		Conditions <sup>(2)</sup>	Тур.	Unit
CIN	Control Input Capacitar	ice		6	pF
Cı/o	Switch Input/Output	A Port	Switch Off	17	pF
	Capacitance	B Port	Switch Off	12	

#### NOTES:

- 1. Capacitance is characterized but not tested.
- 2. Ta =  $25^{\circ}$ C, f = 1MHz, Vin = 0V, Vout = 0V.

## **PIN DESCRIPTION**

Pin Names	I/O	Description			
A, 1B, 2B	I/O	Buses A, 1B, 2B			
SEL0, 1	I	Control Pins for MUX and Switch Enable Functions			
TEST0, 1					

## FUNCTION TABLE(1)

SEL <sub>0</sub>	TEST <sub>0</sub>	Description
L	L	0A to 1B
Н	L	0A to 2B
Х	Н	0A to 1B and 0A to 2B
SEL1	TEST1	Description
L	L	1A to 1B
Н	L	1A to 2B
Х	Н	1A to 1B and 1A to 2B

#### NOTE:

- 1. H = HIGH Voltage Level
  - L = LOW Voltage Level
  - X = DOn't Care

# DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = 5.0V  $\pm 10$ %

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Typ. <sup>(2)</sup>	Max.	Unit
VIH	Control Input HIGH Voltage	Guaranteed Logic HIGH for Cont	Guaranteed Logic HIGH for Control Inputs		_	_	V
VIL	Control Input LOW Voltage	Guaranteed Logic LOW for Contro	ol Inputs	_	_	0.8	V
Іін	Control Input HIGH Current	Vcc = Max.	VI = VCC	_	_	±1	μA
lıL	Control Input LOW Current		Vi = GND	_	_	±1	
Іоzн	Current During	Vcc = Max., Vo = 0 to 5V		_	_	±1	μA
lozl	Bus Switch Disconnect			_	_	±1	
Vik	Clamp Diode Voltage	Vcc = Min., IIN = -18mA		_	-0.7	-1.2	V
loff	Switch Power Off Leakage	Vcc = 0V, Vin or Vo ≤ 5.5V		_	_	±1	μA
Icc	Quiescent Power Supply Current	Vcc = Max., Vin = GND or Vcc		_	0.1	3	μA

# BUS SWITCH IMPEDANCE OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC =  $5.0V \pm 10\%$ 

Symbol	Parameter	Test Conditions	Min.	Тур. <sup>(1)</sup>	Max.	Unit
Ron	Switch On Resistance <sup>(2)</sup>	Vcc = Min., Vin = 0V, Ion = 12mA		5	7	Ω
		Vcc = Min., Vin = 2.4V, Ion = 8mA	_	10	15	
los	Short Circuit Current, A to B <sup>(3)</sup>	A(B) = 0V, B(A) = Vcc	100	_		mA

#### NOTES:

- 1. Typical values are at Vcc = 5.0V,  $+25^{\circ}C$  ambient.
- 2. The voltage drop between the indicated ports divided by the current through the switch.
- 3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

# POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditi	ons <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	Vcc = Max. $Vin = 3.4V(3)$		_	0.5	1.5	mA
ICCD	Dynamic Power Supply Current <sup>(4,5)</sup>	Vcc = Max. One Select Pin Toggling 50% Duty Cycle	VIN = VCC VIN = GND	_	30	40	μΑ/ MHz/ Select
ICCD	Dynamic Power Supply Current <sup>(4,5)</sup>	Vcc = Max. One Test Pin Toggling 50% Duty Cycle	VIN = VCC VIN = GND	_	120	160	μΑ/ MHz/ Test
Ic	Total Power Supply Current <sup>(6)</sup>	Vcc = Max. One Select Pin Toggling	VIN = VCC VIN = GND	_	0.3	0.4	mA
		fi = 10MHz 50% Duty Cycle	VIN = VCC VIN = 3.4V	_	0.6	1.2	
		Vcc = Max. Two Select Pins Toggling	VIN = VCC VIN = GND	_	0.6	0.8	
		fi = 10MHz 50% Duty Cycle	VIN = VCC VIN = 3.4V	_	1.1	2.3	

#### NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type. TA = -40°C to +85°C
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND. Switch inputs do not contribute to  $\Delta Icc$ .
- 4. This parameter represents the current required to switch the internal capacitance of the control inputs at the specified frequency.

  Switch inputs generate no significant power supply currents as they transition. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. CPD = ICCD/VCC
  - CPD = Power Dissipation Capacitance
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
  - $IC = ICC + \Delta ICC DHNT + ICCD (fiN)$
  - Icc = Quiescent Current
  - $\Delta$ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V)
  - DH = Duty Cycle for TTL Inputs High
  - NT = Number of TTL Inputs at DH
  - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
  - fi = Control Input Frequency
  - N = Number of Control Inputs Toggling at fi

# SWITCHING CHARACTERISTICS OVER OPERATING RANGE

 $Following\ Conditions\ Apply\ Unless\ Otherwise\ Specified:$ 

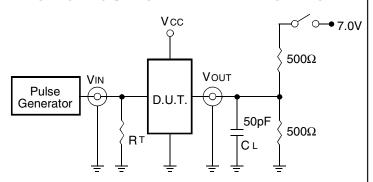
Industrial: TA = -40°C to +85°C, VCC =  $5.0V \pm 10\%$ 

		Vcc = 5V ± 10%		Vcc = 4V			
Symbol	Description <sup>(1)</sup>	Min.	Тур.	Max.	Min.	Max.	Unit
<b>t</b> PLH	Data Propagation Delay	_	_	0.25	_	0.25	ns
<b>t</b> PHL	A to B, B to A <sup>(2)</sup>						
tax	Switch Multiplex Delay	1.5	_	6.5	_	7	ns
	SEL to A						
<b>t</b> PZH	Switch CONNECT Delay	1.5	_	6.5	_	7	ns
tpzl	SEL, TEST to B						
<b>t</b> PHZ	Switch DISCONNECT Delay	1.5	_	7	_	7	ns
tplz	SEL, TEST to B						
Qcı	Charge Injection During Switch DISCONNECT	_	1.5	_	_	_	рС
	TEST to A or B <sup>(3)</sup>						
Qdci	Differential Charge Injection During Multiplexer Switching	_	0.5	_	_	_	рС
	SEL to A or B <sup>(3)</sup>						

#### NOTES:

- 1. See test circuits and waveforms.
- 2. The bus switch contributes no Propagation Delay other than the RC Delay of the load interacting with the RC of the switch.
- 3. |Qc| is the charge injection for a single switch DISCONNECT and applies to either single switches or multiplexers. |Qcc| is the charge injection for a multiplexer as the multiplexed port switches from one path to another. Charge injection is reduced because the injection from the DISCONNECT of the first path is compensated by the CONNECT of the second path.

## TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs

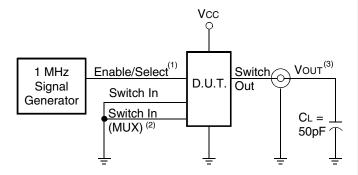
#### **SWITCH POSITION**

Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

#### **DEFINITIONS:**

CL = Load capacitance: includes jig and probe capacitance.

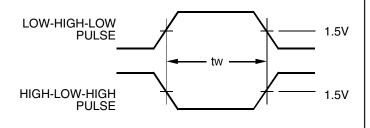
RT = Termination resistance: should be equal to ZouT of the Pulse Generator.



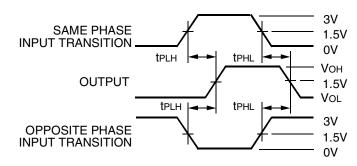
Charge Injection

#### NOTES:

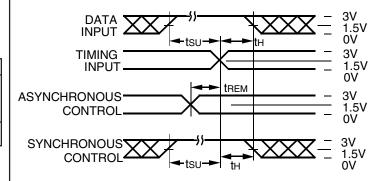
- Select is used with multiplexers for measuring IQDcII during multiplexer select. During all other tests Enable is used.
- 2. Used with multiplexers to measure IQDCII only.
- Charge Injection = ΔVouT CL, with Enable toggling for IQcII or Select toggling for IQpcII. ΔVouT is the change in VouT and is measured with a 10MΩ probe.



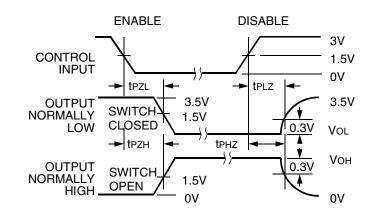
Pulse Width



Propagation Delay



Set-up, Hold, and Release Times

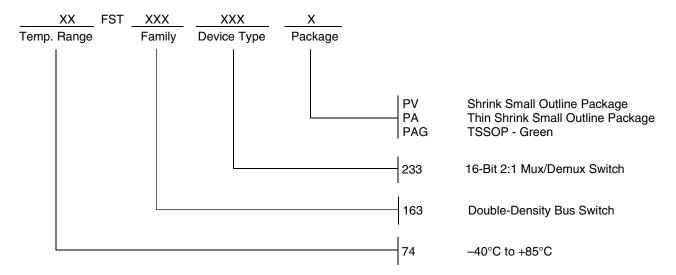


Enable and Disable Times

#### NOTES

- ${\it 1. \ Diagram \ shown \ for \ input \ Control \ Enable-LOW \ and \ input \ Control \ Disable-HIGH.} \\$
- 2. Pulse Generator for All Pulses: Rate  $\leq$  1.0MHz; tF  $\leq$  2.5ns; tR  $\leq$  2.5ns.

# ORDERING INFORMATION





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